

## Electronic Patent Application Fee Transmittal

Application Number:	10520444			
Filing Date:	06-Jan-2005			
Title of Invention:	Hygroscopic molding			
First Named Inventor/Applicant Name:	Teruo Uchibori			
Filer:	Daniel E. Altman			
Attorney Docket Number:	SAEG103.003APC			

Filed as Large Entity

### **U.S. National Stage under 35 USC 371 Filing Fees**

Description	Fee Code	Quantity	Amount	Sub-Total in USD(\$)
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**Basic Filing:**

**Pages:**

**Claims:**

**Miscellaneous-Filing:**

**Petition:**

**Patent-Appeals-and-Interference:**

**Post-Allowance-and-Post-Issuance:**

**Extension-of-Time:**

Extension - 3 months with \$0 paid	1253	1	1020	1020
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Description	Fee Code	Quantity	Amount	Sub-Total in USD(\$)
<b>Miscellaneous:</b>				
<b>Total in USD (\$)</b>				<b>1020</b>